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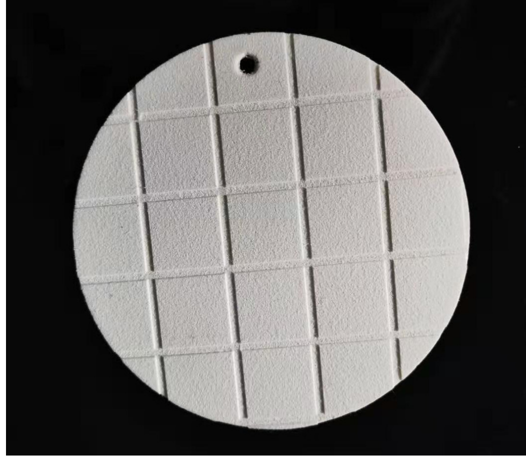
General Information

CMP 600 Polishing Pad
Product Part #: SH-Q13K9-600
Product Description: Aluminum Oxide CMP Pad (Groove)



CMP-600 CMP pad is a **hard surface pad** replicated with 3D technology. The pre-cut groove promotes better stock surface removal.

CMP-600 can be used as sub pad in CMP process.

Material Specification

Pad Surface Parameter	Product Name	Aluminum Oxide CMP Pad
	Pad Density (g/mm3)	0.42 +/- 0.03
	Pad Hardness (Shore A)	78 +/-3
	Pad Thickness (mm)	1.37 +/-0.05
	Groove Pattern (mm)	10*10 +/-0.2
	Groove Width (mm)	1.8 +/-0.02
	Groove Depth (mm)	0.8 +/-0.2
	Outer Diameter	(cut per customer requirement)
Appearance	Surface tear off	Not allow
	Fold mark	Not allow

Main Features for CMP-600 Pad

- Offer higher stock removal.
- Suitable for silicon wafer surface removal.
- Able to work with Silicon Oxide base slurry.